

Japan Packaging Committee Meeting Summary and Minutes

SEMI Japan Standards Spring 2013 Meetings

Monday, March 25, 2013, 15:00-17:00

SEMI Japan, Tokyo, Japan

Next Committee Meeting

SEMI Japan Standards Summer 2013 Meetings

Friday, July 19, 2013, 15:00-17:00

SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Kazunori Kato (AiT), Yutaka Koma (Advisor), Masahiro Tsuruya (iNEMI)

SEMI Staff: Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Renesas Electronics	Shimamoto	Haruo
Renesas Electronics	Hashimoto	Tomoaki	Elpida Memory	Sonobe	Kaoru
AiT	Kato	Kazunori	iNEMI	Tsuruya	Masahiro
Advisor	Koma	Yutaka	Lintec	Watanabe	Kenichi
Disco	Masuchi	Sumio	SEMI Japan	Tejima	Naoko

* alphabetical order by last name

Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
Thin Chip (Die) Bending Strength Measurement Task Force		Haruo Shimamoto (Renesas Electronics) Morihiro Kada (ASET) Shoji Yasunaga (Rohm)

Table 3 Ballot Results

Passed ballots and line items will be forwarded to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
4965C	NEW STANDARD: Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process	Passed

Table 4 Authorized Ballots

None

Table 5 Authorized Activities

#	Type	SC/TF/WG	Details
--	TFOF	Thin Chip (Die) Bending Strength Measurement Task Force	A new task force was chartered to develop standard(s) for Thin Chip (Die) Bending Strength Measurement.

Table 6 New Action Items (or move to Section 8, Action Item Review)

Item #	Assigned to	Details
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved
PKG130325-1	SEMI	To forward adjudication result of Doc.4965C to the ISC A&R Subcommittee for procedural review.
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff
PKG130325-3	SEMI	To publish G92 Related Information

1 Welcome, Reminders and Introductions

Masahiro Tsuriya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on December 6, 2012.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Yutaka Koma (Advisor) / Kazunori Kato (AiT)

Discussion: None

Vote: 7 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_Packaging_Previous_Mtg_Minutes_130325

4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2013 Calendar of Events, NA Standards Spring 2013 Meetings, 2013 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, ISC Audits & Reviews SC Summary, New Standards Ballot and Membership Systems, New Ballot Formatting Templates, Style Manual and Compilation of Terms, Revised SEMI Regulations & Procedure Guide and Contact Information.

Attachment: 02_SEMI_Staff_Report_130325

5 Liaison Reports

5.1 North America 3DS-IC Committee Report

Naoko Tejima briefly reported for the North America 3DS-IC Committee. This report included Leadership, Organization Chart, Task Force Overview, SNARFs, Document Review Summary, Meeting Information, NA 3DS-IC Ballots and NA 3DS-IC Spring 2013 Meeting Schedule.

Attachment: 03_NA_3DS-IC_Comm_Report_130325

5.2 Taiwan 3DS-IC Committee Report

Naoko Tejima briefly reported for the Taiwan 3DS-IC Committee. This report included Organization Chart, Task Force Overview, SNARFs, Meeting Information and Available Taiwan 3DS-IC Ballots.

Attachment: 04_TW_3DS-IC_Comm_Report_130325

6 Ballot Review

6.1 Doc.4965C, New Standard: Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process

This document passed committee review as balloted and will be forwarded to the ISC A&R SC for procedural review.

Although there was a reject voting, the voter withdrew it on condition that the concerned items will be considered in the next revision. Sumio Masuchi reported about the discussion between a reject voter and TF as follows:

- It does not have high potential that the packaging equipment exceed 2410 mm height.
- Since there is not the standards about Load Port at the moment, the designing of 450mm equipment is not able to be started. There is an urgent need the related standards to be published.

Action Item: SEMI staff to forward adjudication result of Doc.4965C to the ISC A&R Subcommittee for procedural review.

Attachment: 05_4965C_Ballot_Report_130325

7 The 3D-IC Pavilion at SEMICON Japan 2013

Collins Junko explained that SEMI is planning some special pavilions and workshop at "SEMICON Japan 2013" and one of them is for 3D-IC. SEMI asked the 3D-IC Study Group to cooperate and support it.

Action Item: 3D-IC Study Group to discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff

Attachment: 06_SJ13_Advanced_Technology_Pavilion_130325_(JA_only)

8 Task Force Reports

8.1 Electromagnetic Characterization Study Group

Naoko Tejima gave the report from Mikio Kiyono, the leader of the Electromagnetic Characterization Study Group.

- The Electromagnetic Characterization Study Group is planning to hold a workshop with JEITA standards activities

Attachment: 07_Electromagnetic_Characterization_SG_Report_130325_(JA_only)

8.2 Packages and Packaging Materials Eco-efficiency Task Force

No report was provided by the Task Force.

8.3 Wafer Shipping Container for Assembly & Packaging Task Force

No report was provided by the Task Force.

8.4 DFM Study Group

Instead of the DFM Study Group leader, Kazunori Kato reported that the Study Group has reported as follows.

- The workshop will be also held together with Electromagnetic Characterization Study Group.

8.5 Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported on progress for Japan Assembly & Test Die Preparation Task Force. *Doc.4965C, New Standard: Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process* passed committee review as previously discussed. Taskforce plans to launch the revision of the above document according to the previous voting result (Withdrawn Reject) after it will be published.

The Task Force has also completed “Related Information” of “SEMI G92-0412, Specification for Tape Frame Cassette for 450 mm Wafer”.

Motion: To publish G92 Related Information

By / 2nd: Sumio Masuchi (Disco)/ Kazunori Kato (AiT)

Discussion: None.

Vote: 7 in favor and 0 opposed. **Motion passed.**

Action Item: SEMI to publish G92 Related Information

Attachment: 08_G92_Related_Information_130325

Note: Since the procedure was incomplete, it will be gone through re-procedure at the next committee meeting.

8.6 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group. Study Group meeting has been held about once a month and mainly has been discussed about the possibility of the standardization of Bonded Wafer Handling and Grip Ring.

As the first result of the progress, TFOF to form Thin Chip (Die) Bending Strength Measurement Task Force was submitted.

Motion: To approve TFOF for Thin Wafer(die) Bending Strength Measurement TF.

By / 2nd: Masahiro Tsuruya (iNEMI)/ Haruo Shimamoto (Renesas Electronics)

Discussion: None.

Vote: 8 in favor and 0 opposed. **Motion passed.**

Attachment: 09_TFOF_for_Thin_Wafer(die)_Bending..._TF_130325

9 Old Business

9.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

Item #	Assigned to	Details
PKG111125-1	Sumio Masuchi	To draft a related document for Doc. 4814A (New Standard: Specification for Tape Frame Cassette for 450 mm Wafer) Closed
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee Open
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved Open
PKG121206-1	Japan Assembly & Test Die Preparation Task Force	To submit Doc.#4965C for Cycle 1, 2013. Closed



10 New Business

None

11 Action Item Review

11.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

12 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Friday, July 19, 2013, 15:00-17:00, at SEMI Japan, Tokyo, Japan.



Respectfully submitted by:
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Minutes approved by:

Kazunori Kato (AiT), Co-chair	May 8, 2013
Yutaka Koma (Advisor), Co-chair	May 8, 2013
Masahiro Tsuruya (iNEMI), Co-chair	May 8, 2013

Table 8 Index of Available Attachments #1

#	<i>Title</i>
1	JA_Packaging_Previous_Mtg_Minutes_130325
2	SEMI_Staff_Report_130325
3	NA_3DS-IC_Comm_Report_130325
4	TW_3DS-IC_Comm_Report_130325
5	4965C_Ballot_Report_130325
6	SJ13_Advanced_Technology_Pavilion_130325_(JA_only)
7	Electromagnetic_Characterization_SG_Report_130325_(JA_only)
8	G92_Related_Information_130325
9	TFOF_for_Thin_Wafer(die)_Bending..._TF_130325

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.